



## The Midwest Microelectronics Consortium Announces Hiring of Director of Programs

**FOR IMMEDIATE RELEASE – Beaver Creek, Ohio July 15, 2024**

The Midwest Microelectronics Consortium (MMEC), one of the eight initial Awardees of Microelectronics Commons funding, is excited to announce the hiring of Director of Programs Mr. Glen “David” Via, effective June 17<sup>th</sup>, 2024. In this role, Mr. Via will establish, refine, and drive processes and oversee the technical and programmatic execution of projects and infrastructure within the organization.

“Dave’s appointment as Director of Programs reflects his outstanding track record and expertise in microelectronics, as well as his deep understanding of technology development in the laboratory through commercialization,” stated Jackie Janning-Lask, MMEC CEO. “His passion for leading strong technology and operations teams, his ability to navigate complex business and government challenges, and his drive to move technology from lab-to-fab-to-mission, makes him the ideal choice to lead our technology initiatives.”

Mr. Via comes to the MMEC from the DoD’s Anti-Tamper Executive Agent (ATEA) office where he served as Technical Director. His primary responsibilities included developing innovative solutions to mission-critical problems, establishing policies and procedures, and engaging with the broader USG microelectronics community to foster collaborations. Prior to the ATEA, Mr. Via worked for nearly four decades in the Sensors Directorate of the Air Force Research Laboratory (AFRL/Ryd). Early research efforts as a process engineer focused on III-V and III-N device development where he participated in nearly every facet of operations from device design and fabrication through testing and physical characterization. In the early 2000s, Mr. Via moved outside the cleanroom to lead independent validation and test efforts for national-level wide bandgap technology development programs establishing characterization and reliability evaluation processes, coordinating activities across multiple organizations and services, and documenting findings. Later in his career at AFRL, Mr. Via became Technical Advisor for Trusted Electronics leading a Trust and Assured Microelectronics (T&AM) Technical execution Area (TEA) and overseeing AFRL V&V activities related to the evaluation of microelectronics. Mr. Via rounded out his time at the Sensors Directorate as the Core Technical Competency (CTC) lead for Enabling Devices and Components where he provided technical oversight and strategic vision for the electronics devices, EO/IR components, highly integrated microsystems, and sensor subsystem portfolio.

“I’m excited to be joining the MMEC and look forward to engaging with the consortium membership to drive technical innovation. The microelectronics development strategy and processes being established by the MMEC are going to change the semiconductor landscape and I’m thrilled to be part of the team that is going to make that happen,” said Via. “The consortium structure and MMEC leadership commitment to providing ongoing value to the membership will foster the collaboration and teaming needed for successful technology development.”

For more information about the MMEC please visit our website at [mmeconsortium.org](http://mmeconsortium.org)

### **About the MMEC**

The Midwest Microelectronics Consortium (MMEC) leads the acceleration of microelectronic technologies and delivers solutions to establish a trusted and resilient domestic supply chain. The MMEC is the premier collaborative, public-private ecosystem that engages broadly across innovative partners in industry, academia, and government to rapidly advance defense and commercial applications. This unique environment empowers members to discover new technologies, share capabilities, develop a skilled workforce, and launch groundbreaking innovation into scalable commercial production for the benefit of National Security and economic dominance.

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